

FIG. 1 is a perspective view of a rectangular frame assembly 100. The assembly includes a frame 102 with a top edge 103 and a bottom edge 104. A central opening 105 is defined by a dashed line. Four corner fasteners 120 are positioned at the corners of the opening 105.

[illegible]

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Fig. 2

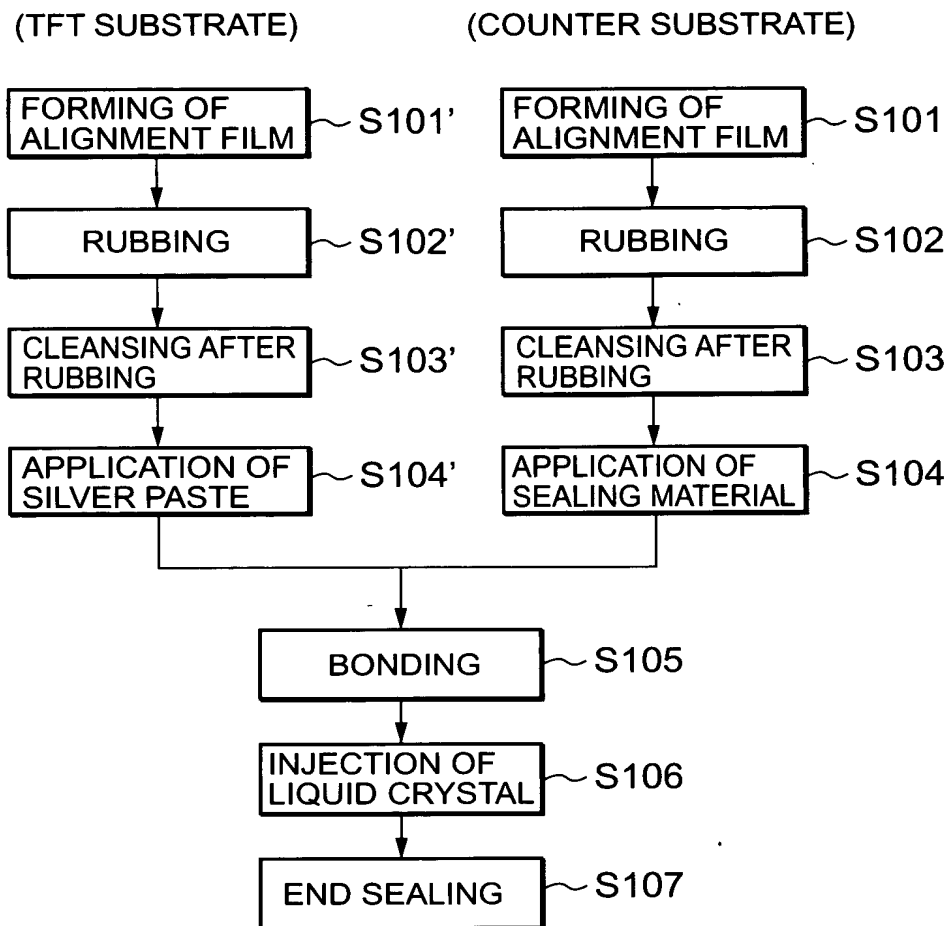
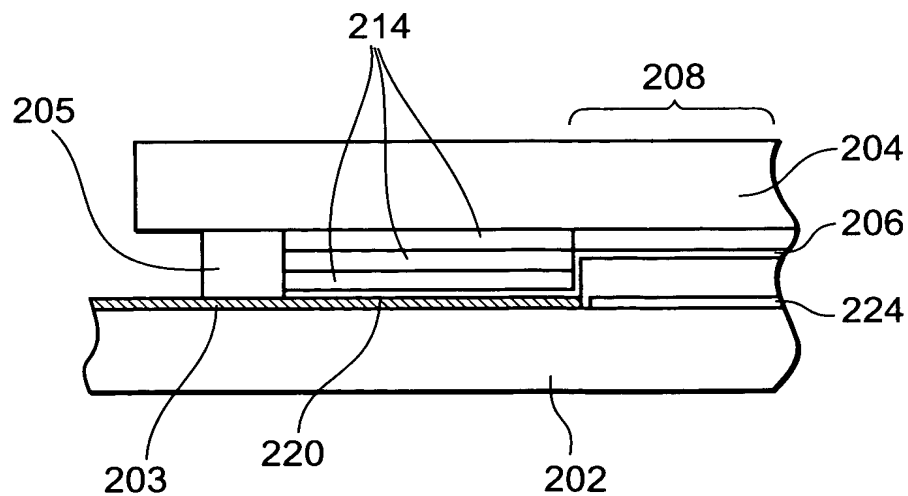
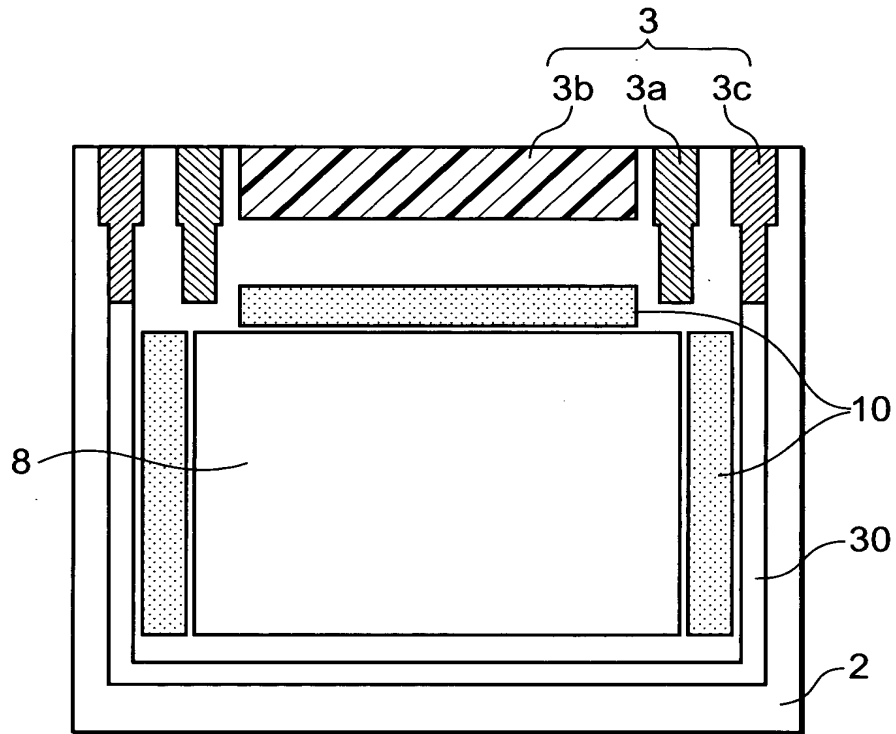


Fig. 3

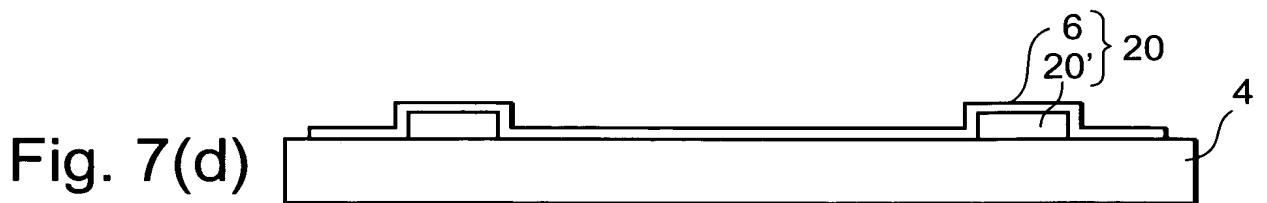
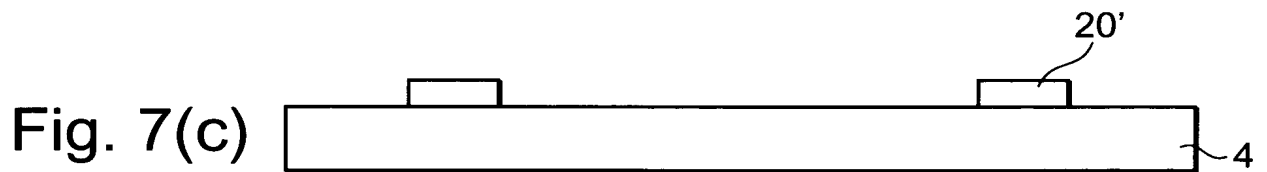
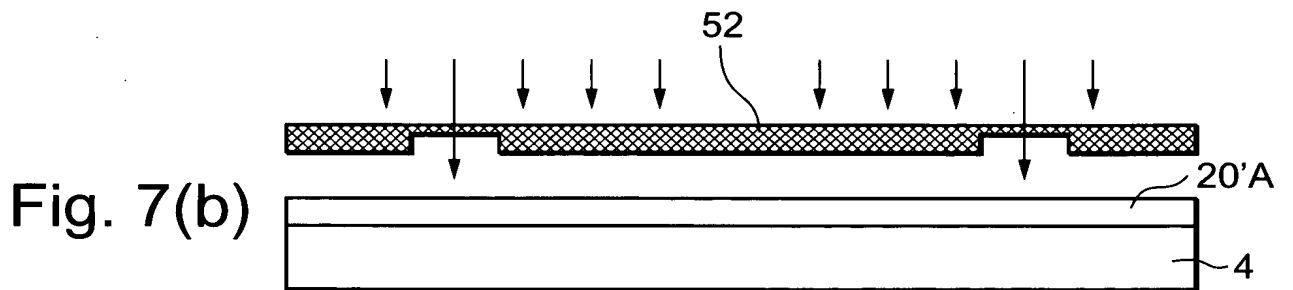
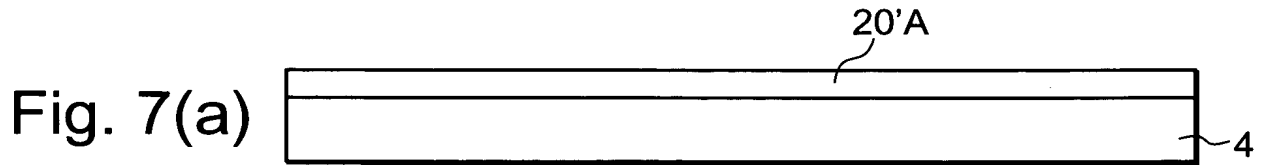


A cross-sectional view of a semiconductor device. The device features a substrate 302 with a trench 304. A gate structure 306 is formed on the side of the trench. A conductive layer 314 is deposited on the bottom of the trench. A contact pad 320 is formed on the conductive layer 314. A passivation layer 325 is formed on the top of the device. A contact pad 326 is formed on the passivation layer 325. A cross-section line A-A is indicated on the left side of the device.

Fig. 5



[illegible]



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Fig. 8

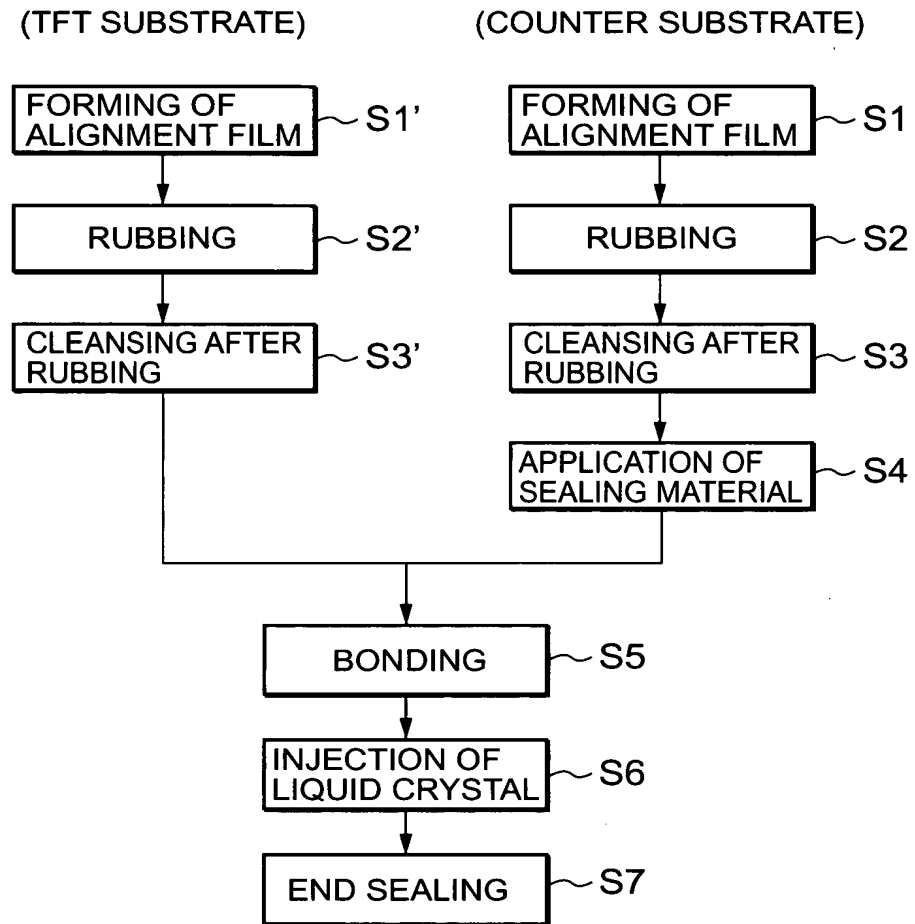


Fig. 9(a)

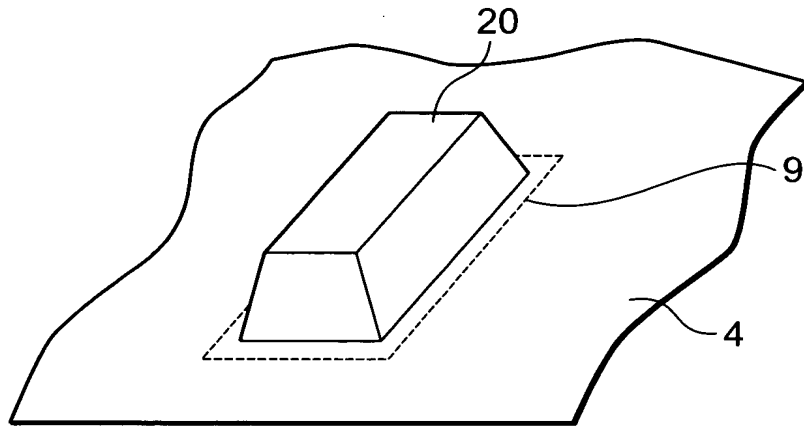


Fig. 9(b)

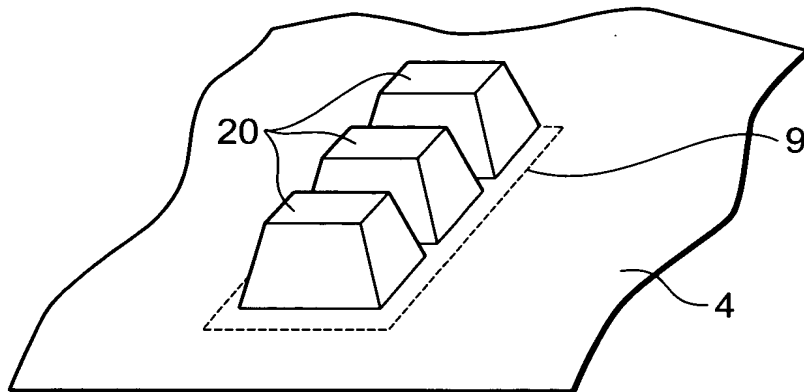
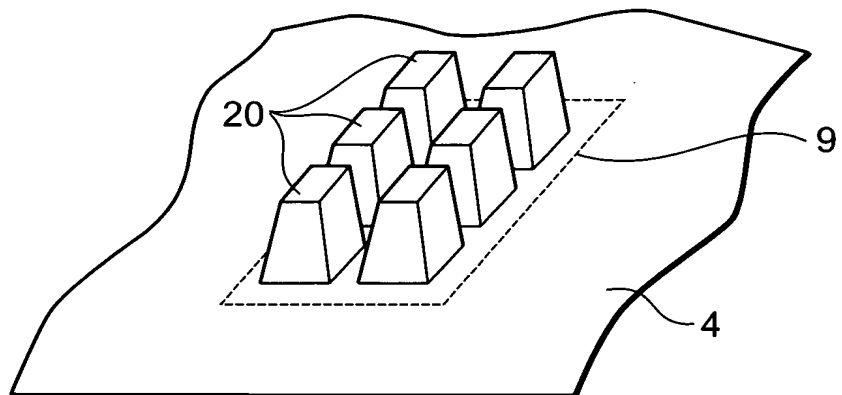


Fig. 9(c)





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Fig. 10

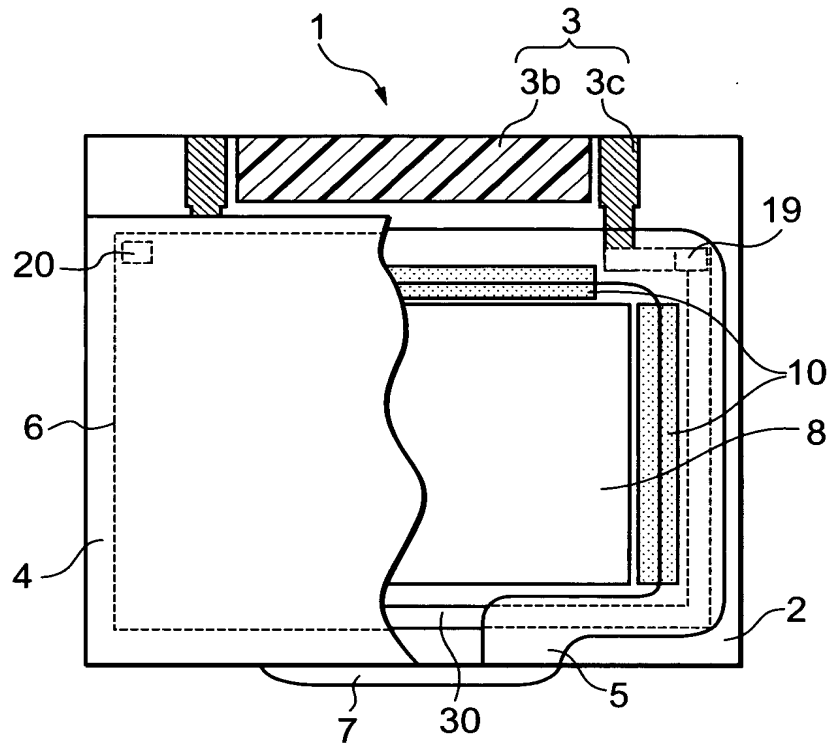
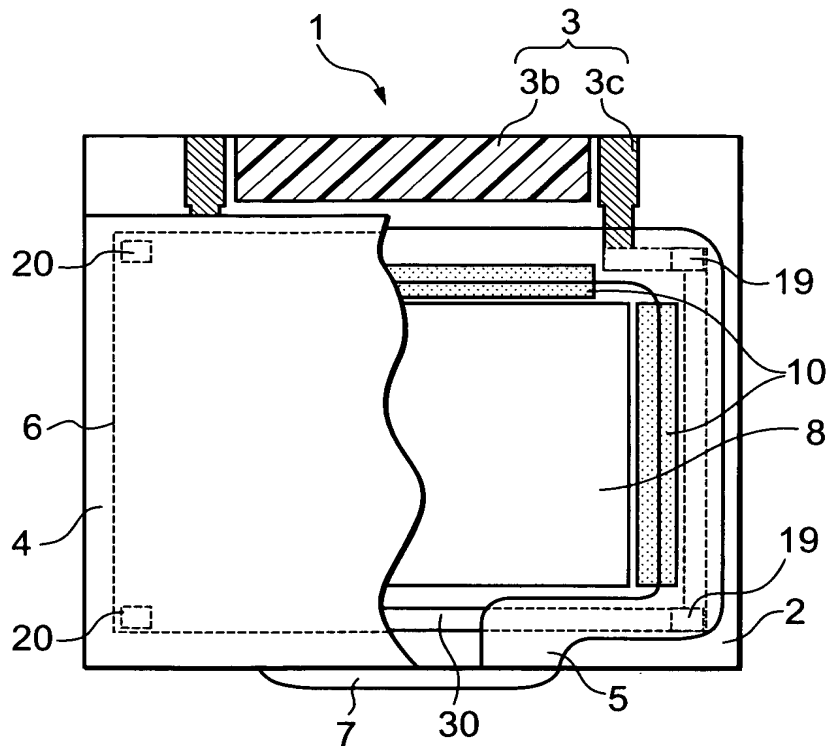
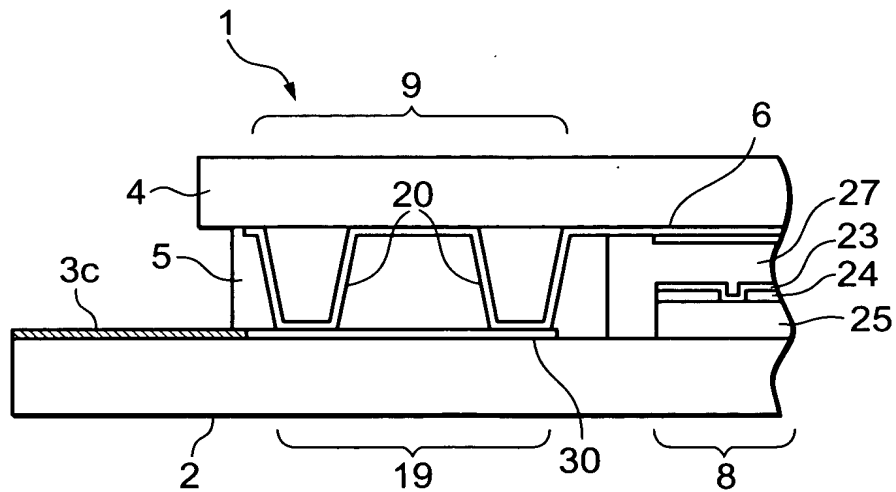


Fig. 11





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Fig. 13(a)

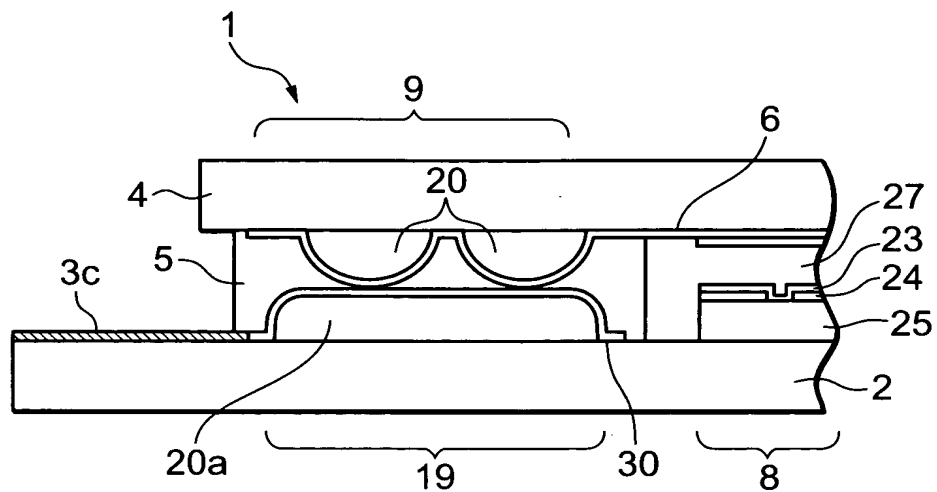


Fig. 13(b)

